

Application Serial No. 10/800,603
Reply to Office Action of May 5, 2005

PATENT
Docket: CU-3637

Amendments To The Claims

The listing of claims presented below will replace all prior versions, and listings, of claims in the application.

Listing of claims:

1. (original) A semiconductor device substrate, comprising:
 - a substrate body having a wiring layer;
 - a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and
 - a reinforcing member larger than the opening forming portion, provided in said substrate body at a portion corresponding to the opening forming portion, and reinforcing said substrate body at the portion corresponding to the opening forming portion.
2. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is a circuit board having a capacitor part that electrically connects the semiconductor element and the wiring layer.
3. (original) The semiconductor device substrate as claimed in claim 2, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
4. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is an interposer having a via that directly electrically connects the semiconductor element and the wiring layer.

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5. (original) The semiconductor device substrate as claimed in claim 4, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
6. (original) The semiconductor device substrate as claimed in claim 1, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.
7. (currently amended) A manufacturing method of a substrate, said manufacturing method comprising the steps of:
 - manufacturing a reinforcing member;
 - arranging the reinforcing member on a base at a portion corresponding to an opening forming portion of the base;
 - forming a substrate body on the base on which the reinforcing member is arranged so that the reinforcing member is provided in said substrate, said substrate body including a wiring layer and made of a material that is different from a material of the base; and
 - forming the opening forming portion smaller than the reinforcing member, thereby exposing a part of the reinforcing member at the opening forming portion.
8. (original) The manufacturing method as claimed in claim 7, wherein the step of manufacturing the reinforcing member includes a step of forming a capacitor on a core member.
9. (original) The manufacturing method as claimed in claim 8, wherein the step of manufacturing the reinforcing member includes a step of forming a via penetrating the core member.
10. (original) The manufacturing method as claimed in claim 9, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

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11. (original) The manufacturing method as claimed in claim 8, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.'

12. (original) The manufacturing method as claimed in claim 7, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

13. (currently amended) A semiconductor device, comprising:

the semiconductor device substrate comprising: as claimed in claim 1

a substrate body having a wiring layer;

a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and

a reinforcing member larger than the opening forming portion, provided in said substrate body at a portion corresponding to the opening forming portion, and reinforcing said substrate body at the portion corresponding to the opening forming portion; and

a semiconductor element mounted in the opening forming portion of the semiconductor device substrate.

14. (currently amended) A semiconductor device of claim 13, wherein the reinforcing member is a circuit board having a capacitor part that electrically connects the semiconductor element and the wiring layer.

~~, comprising the semiconductor device substrate as claimed in claim 2;~~

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and

~~a semiconductor element mounted in the opening forming portion of the
semiconductor device substrate.~~

15. (currently amended) A semiconductor device of claim 14, wherein the
reinforcing member is arranged on the base via an abutting member made of a
metal.

~~, comprising the semiconductor device substrate as claimed in claim 3;~~

and

~~a semiconductor element mounted in the opening forming portion of the
semiconductor device substrate.~~

16. (currently amended) A semiconductor device of claim 15, wherein the
reinforcing member is an interposer having a via that directly electrically
connects the semiconductor element and the wiring layer.

~~, comprising the semiconductor device substrate as claimed in claim 4;~~

and

~~a semiconductor element mounted in the opening forming portion of the
semiconductor device substrate.~~

17. (currently amended) A semiconductor device of claim 16, wherein the
reinforcing member is arranged on the base via an abutting member made of a
metal.

~~, comprising the semiconductor device substrate as claimed in claim 5;~~

and

~~a semiconductor element mounted in the opening forming portion of the~~

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~~semiconductor device substrate.~~

18. (currently amended) A semiconductor device of claim 17, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

~~, comprising the semiconductor device substrate as claimed in claim 6;~~

and

~~a semiconductor element mounted in the opening forming portion of the semiconductor device substrate.~~

19. (new) A semiconductor device substrate, comprising:

a substrate body having a wiring layer;

a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted; and

a reinforcing member being larger than the opening forming portion, provided in said substrate body at a portion corresponding to the opening forming portion so that a part of the reinforcing part is embedded in the substrate body, and reinforcing said substrate body at the portion corresponding to the opening forming portion.